

UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE PATENT TRIAL AND APPEAL BOARD

INNOSCIENCE AMERICA, INC.,
PETITIONER,

V.

INFINEON TECHNOLOGIES AUSTRIA AG,
PATENT OWNER.

Case No. IPR2025-00175
U.S. Patent 8,686,562

PETITIONER'S UPDATED EXHIBIT LIST

Further to 37 C.F.R. § 42.63(e), Petitioner hereby submits a current listing of its exhibits to counsel for Patent Owner. Exhibit 1048 was filed on P-TACTS and served via email to counsel of record for the Patent Owner.

Exhibits	Description
Ex-1001	U.S. Patent No. 8,686,562 (“the ’562 patent”)
Ex-1002	Expert Declaration of Dr. Yuji Zhao (“Zhao”)
Ex-1003	Curriculum Vitae of Dr. Yuji Zhao
Ex-1004	U.S. Patent No. 5,943,601 to Usui et al. (“Usui”)
Ex-1005	U.S. Patent Publication No. 2010/0052066 to Yu et al. (“Yu”)
Ex-1006	U.S. Patent Publication No. 2008/0023726 to Adesida et al. (“Adesida”)
Ex-1007	U.S. Patent No. 7,777,252 to Sugimoto et al. (“Sugimoto”)
Ex-1008	Pearson et al., <i>Gallium Nitride Processing for Electronics, Sensors and Spintronics</i> , Springer, 10.1007/1-84628-359-0. (2006)
Ex-1009	Adachi, <i>Properties of Group-IV, III–V and II–VI Semiconductors</i> , John Wiley & Sons, Ltd, 10.1002/0470090340 (2005)
Ex-1010	U.S. Patent Publication No. 2007/0164321 to Sheppard et al. (“Sheppard”)
Ex-1011	Mishra et al., <i>Semiconductor Device Physics and Design</i> , Springer (2008)
Ex-1012	Wu et al., <i>Very-High Power Density AlGaIn/GaN HEMTs</i> , IEEE Transactions on Electronic Devices, Vol. 48, No. 3, March 2001
Ex-1013	Quay, <i>Gallium Nitride Electronics</i> , Springer, 10.1007/978-3-540-71892-5. (2008)

Exhibits	Description
Ex-1014	Mishra et al., <i>AlGaIn/GaN HEMTs—An Overview of Device Operation and Applications</i> , Proceedings of the IEEE, Vol. 90, No. 6, June 2002
Ex-1015	Neaman, <i>Semiconductor Physics and Devices</i> , 3 rd edition (2002)
Ex-1016	Voss, <i>Thermally Stable Ohmic and Schottky Contacts to GaN</i> , University of Florida, 2008
Ex-1017	Krämer, <i>Fabrication and characterization of metal-semiconductor contacts for application in Al_xGa_{1-x}N/GaN HEMTs</i> , (Oct. 31, 2000)
Ex-1018	Kuzmik et al., <i>Technology and Performance of InAlN/AlN/GaN HEMTs With Gate Insulation and Current Collapse Suppression Using ZrO₂ or HfO₂</i> , IEEE TRANSACTIONS ON ELECTRON DEVICES, Vol. 55, No. 3, Mar. 2008
Ex-1019	Wu et al., <i>Aluminum, magnesium, and gold contacts to contamination free n-GaN surfaces</i> , Journal of Applied Physics, Vol. 89, No. 1, Jan. 1, 2001
Ex-1020	Foresi et al., <i>Metal contacts to gallium nitride</i> , Appl. Phys. Lett., Vol. 62, No. 22, May. 31, 1993
Ex-1021	Kayali et al., <i>GaAs MMIC Reliability Assurance Guideline for Space Applications</i> , JPL Publication 96-25, Dec. 15, 1996
Ex-1022	U.S. Patent Publication No. 2009/0250816 to Chin et al. (“Chin”)
Ex-1023	U.S. Patent No. 7,335,590 to Suh et al. (“Suh”)
Ex-1024	U.S. Patent No. 6,607,976 to Chen et al. (“Chen”)
Ex-1025	Excerpts from Bauccio, Michael, <i>Refractory Metals</i> , ASM Metals Reference Book, ASM International, American Society for Metals, ISBN 978-0-87170-478-8, (1993)
Ex-1026	Preuss, <i>Finer Copper Wires Make for Faster Integrated Circuits</i> , Berkeley Lab, https://www2.lbl.gov/Science-Articles/Archive/integrated-circuits-copper.html , Apr. 5, 1999

Exhibits	Description
Ex-1027	Cockeram, <i>The Diffusion Bonding of Silicon Carbide and Boron Carbide Using Refractory Metals</i> , USDOE Contract No. DE-AC1 1-98PN38206, Nov. 22, 1999
Ex-1028	Kim, <i>Atomic Layer Deposition of Metal and Nitride Thin films: Current Research Efforts and Applications for Semiconductor Device Processing</i> , RC22737 (W0303-012), Mar. 5, 2003
Ex-1029	U.S. Patent No. 6,844,258 to Fair et al. (“Fair”)
Ex-1030	U.S. Patent No. 4,980,752 to Jones, Jr. (“Jones”)
Ex-1031	U.S. Patent No. 5,635,763 to Inoue et al. (“Inoue”)
Ex-1032	U.S. Patent No. 6,646,352 to Ohmi et al. (“Ohmi”)
Ex-1033	Order Staying and Conditionally Closing Case, <i>Infineon Tech. Austria AG v. Innoscience (Suzhou) Tech. Company, Ltd.</i> , No. 4:24-cv-01553 (N.D. Ca. Aug. 30, 2024), ECF No. 56
Ex-1034	Excerpts from Prosecution History of the ’562 Patent
Ex-1035	Excerpts from Rooy, E.L., <i>Introduction to Aluminum and Aluminum Alloys</i> , Metals Handbook, 10 th Edition, Volume 2 Properties and Selection: Nonferrous Alloys and Special-Purpose Materials, ASM International, ISBN 978-0-87170-378-1, (October 1990)
Ex-1036	Pierson, Hugh O., <i>The Refractory Nitrides</i> , Handbook of Refractory Carbides and Nitrides, Properties, Characteristics, Processing and Applications, ISBN 978-0-8155-1392-6, (1996)
Ex-1037	Construing Certain Claim Terms, <i>Certain Semiconductor Devices and Products Containing the Same</i> , Inv. No. 337-TA-1414, Order No. 29 (Apr. 4, 2025)
Ex-1038	U.S. Patent Application Publication No. 2006/0124954 to Akaishi (“Akaishi”)
Ex-1039	Songyuan Dai et al., <i>Design of DSC panel with efficiency more than 6%</i> , Solar Energy Materials & Solar Cells 85 (2005) 447–455

Exhibits	Description
Ex-1040	U.S. Patent No. 5,940,732 to Zhang (“Zhang”)
Ex-1041	U.S. Patent Application Publication No. 2007/0210350 to Omura et al. (“Omura”)
Ex-1042	U.S. Patent No. 7,381,993 to Uchida et al. (“Uchida”)
Ex-1043	U.S. Patent Application Publication No. 2007/0108585 to Pavier et al. (“Pavier”)
Ex-1044	U.S. Patent Application Publication No. 2006/0258143 to Kuo (“Kuo”)
Ex-1045	U.S. Patent Application Publication No. 2007/0190803 to Singh et al. (“Singh”)
Ex-1046	<i>Wiley Electrical and Electronics Engineering Dictionary</i> (excerpt) 2004
Ex-1047	Supplemental Declaration of Yuji Zhao, Ph.D.
Ex-1048	Petitioner’s Demonstratives for Oral Hearing

Dated: April 6, 2026

By: /Lionel M. Lavenue/
 Lionel M. Lavenue, Lead Counsel
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CERTIFICATE OF SERVICE

The undersigned hereby certifies that the foregoing **Petitioner's Updated Exhibit List and Exhibit 1048** were served on April 6, 2026, via email directed to counsel of record for the Patent Owner at the following:

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